MATERIAL DECLARATION SHEET

BOURNS®

Package Type	PTVS1-380C-TH		
Product Line	Semiconductor products		
Compliance Date	27th Sep 2018		
RoHS Compliant	Yes	MSL	N/A

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.1280	Bisphenol Copolymer	25036-25-3	60.00	3.41	5.69
				Alumina Trihydrate	21645-51-2	15.00	0.85	
				Fused Silica	60676-86-0	20.00	1.14	
				Hydrated Iron Oxide	20344-49-4	1.50	0.09	
				Titanium Dioxide	13463-67-7	1.50	0.09	
				Melamine Cyanurate	37640-57-6	1.50	0.09	
				Amine Adduct	Trade Secret	0.50	0.03	
2	Electrodes	Copper Alloy	1.4597	Copper	7440-50-8	99.10	64.26	64.85
				Silver	7440-22-4	0.40	0.26	
				Misc. not to declare	-	0.50	0.32	
3	Terminations	Copper Alloy	0.4460	Copper	7440-50-8	99.50	19.71	19.81
				Misc. not to declare	-	0.50	0.10	
4	Chip	Silicon	0.1120	Silicon	7440-21-3	85.34	4.25	4.98
				Aluminum	7429-90-5	5.13	0.26	
				Nickel	7440-02-0	9.09	0.45	
				Gold	7440-57-5	0.44	0.02	
5	Die Attach	Solder	0.0303	Lead	7439-92-1	92.50	1.24	1.35
				Tin	7440-31-5	5.00	0.07	
				Silver	7440-22-4	2.50	0.03	
6	Die Coating	Silicone	0.0750	Polysiloxane	63148-62-9	22.11	0.74	3.33
				Chromium Sesquioxide	1308-38-9	5.67	0.19	
				Fumed Silica	112945-52-5	11.11	0.37	
				Filler	Trade Secret	61.11	2.04	
		Total Weight:	2.2510					

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society

* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

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